

**TECHNICAL PROCEEDINGS OF THE EPC (EUROPEAN PCB CONVENTION)**

*Copies of the Technical Proceedings of the EPC(EUROPEAN PCB CONVENTION) which was held at Germany between 29th September and 1st October 1998 are available in IPCA's Office for sale to IPCA MEMBERS ONLY. These proceedings include valuable, useful and interesting technical articles pertaining to PCB manufacture and its advances, as you could see from the copy of the contents furnished herewith.*

*It is brought to the kind notice of all IPCA members that it has been decided in the Executive Committee meeting held at Delhi on 31st October 1998 to make available these Proceedings to all members at a reasonable cost of Rs. 1500/- per copy. The total number of pages of the Proceedings is approximately 300.*

*Members who are desirous to possess a copy of the same, may please write to us duly enclosing a cheque/DD for Rs. 1500/- drawn in the name of INDIAN PRINTED CIRCUIT ASSOCIATION, BANGALORE, so that necessary immediate action will be taken by IPCA to send a copy of the same on receipt of the cheque/DD.*

**EPC European PCB Convention  
PROCEEDINGS**

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